



Platform for Photonic Packaging Technology

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What is ePIXnet ?









(Sep 2004 – Aug 2006)

- referees & commission: implement research integration in structure
- re-evaluate research activities



(since September 2006)



Joint Research Activities





ePIXnet Platforms



ePIXnet Platforms

Packaging Platform

Contact: <http://claudia.intec.ugent.be/packaging/index.php?id=6>)



Platform on Photonics Packaging

- We are a Service Provider for packaging solutions in photonics
- Organization of Centres of Expertise in the field
- Access via coordinator (TU Berlin)



Fraunhofer
Institut
Nachrichtentechnik
Heinrich-Hertz-Institut



Fraunhofer
Institut
Zuverlässigkeit und
Mikrointegration



TU Berlin



University of Twente
Enschede - The Netherlands

• Function

- support parties who seek assessment of photonic devices
- provide packaging for prototype testing

• Offered

- packaging & assembly (pigtailling, butterfly housing etc) + advanced technology base for new developments
- assistance with prototype development, production, testing, characterisation; pre-production fabrication, small batches & samples



How does it work?

Example: Joint Research Activity SOI Modulators

Goal

- develop high performance compact Silicon modulators

consortium of groups from

- Spain
- France
- Denmark
- UK

(Source: A. Liu, High-speed optical modulator, nature, 427, p 615)

Example: Joint Research Activity SOI Modulators

Groups from
Spain, France

Conceptual design / simulations
(MZI, injection structure, ...)

Silicon Photonics
Platform

Mask layout, fabrication
(DRC, 8" processing, ...)

Packaging
Platform

Pigtailing, RF-Assembly

Groups from
Spain, France

Test & Measurement



Appeal

- no detailed technology know-how required
- fabless design & fabrication model until module stage

Nota bene (Research Integration)

- infrastructural goal of the EU
- important theme within FP7
- this also applies to optoelectronic packaging

Invitation to present yourself

- list link
- be included in the newsletter
- offer your service to ePIXnet

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